

## General Description

The Sanrise SRC65R330B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R330B break down voltage is 650V and it has a high rugged avalanche characteristics.

The SRC65R330B is available in TO-220F , TO-220C and TO-252 packages.

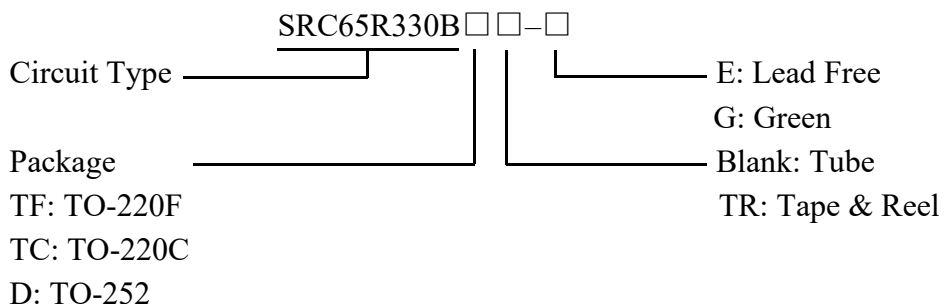
## Features

- Ultra Low  $R_{DS(ON)} = 330m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g = 25.8nC$  typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified
- Ultra-fast body diode

## Application

- PC Power
- Server / Telecom
- High Performance LED Lighting Power

## Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-220F	SRC65R330BTF-G	SRC65R330BTFG	Tube
TO-220C	SRC65R330BTC-G	SRC65R330BTCG	Tube
TO-252	SRC65R330BDTR-G	SRC65R330BDG	Tape & Reel

## Symbol

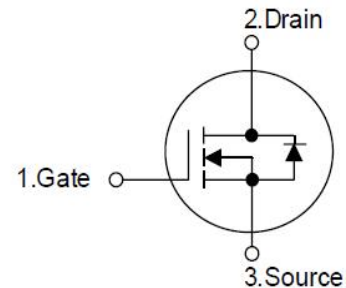


Figure 1 Symbol of SRC65R330B

## Package Type

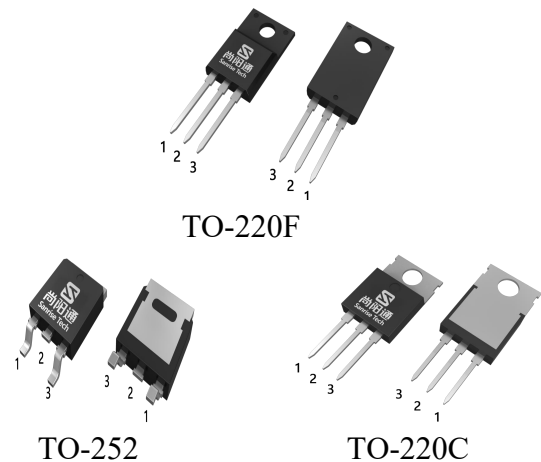


Figure 2 Package Types of SRC65R330B

## Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Drain-Source Voltage (Note2)		$V_{DSS}$	650	V
Gate-Source Voltage		$V_{GSS}$	±30	V
Gate-Source Voltage, AC ( $f > 1$ Hz)		$V_{GSS}$	±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	12.0	A
	$T_C = 100^\circ\text{C}$		7.6	
	$T_C = 125^\circ\text{C}$		5.4	
Power Dissipation ( $T_C = 25^\circ\text{C}, \text{TO-252}, \text{TO-220C}$ )		$P_{tot}$	86	W
Power Dissipation ( $T_C = 25^\circ\text{C}, \text{TO-220F}$ )		$P_{tot}$	32	W
Pulsed Drain Current (Note 3)		$I_{DM}$	36	A
Avalanche Energy, Single Pulse (Note 4)		$E_{AS}$	185	mJ
Avalanche Energy, Repetitive (Note 3)		$E_{AR}$	0.2	mJ
Avalanche Current, Repetitive (Note 3)		$I_{AR}$	3.5	A
Continuous Diode Forward Current		$I_S$	12.0	A
Diode Pulse Current		$I_{S,PULSE}$	35	A
Operating Junction Temperature		$T_J$	150	$^\circ\text{C}$
Storage Temperature		$T_{STG}$	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	$^\circ\text{C}$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- For voltage spike during switching.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 2\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

## Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F	$R_{thJC}$			3.85	$^\circ\text{C} / \text{W}$
	TO-252				1.44	
	TO-220C				1.44	
Thermal resistance, Junction-to-Ambient	TO-220F	$R_{thJA}$			70	$^\circ\text{C} / \text{W}$
	TO-252				62	
	TO-220C				62	

**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			10	$\mu A$
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3.0	4.0	5.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=5.0A$		250	330	$m\Omega$
Gate Resistance	$R_G$	$f=1MHz, \text{Open Drain}$		2.0		$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		1140		pF
Output Capacitance	$C_{OSS}$			74		
Reverse Transfer Capacitance	$C_{RSS}$			15		
Effective output capacitance, energy related <sup>NOTE5</sup>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 480V$		47.0		pF
Effective output capacitance, time related <sup>NOTE6</sup>	$C_{O(tr)}$			201		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=5.5A, R_G=10\Omega, V_{GS}=10V$		12		ns
Rise Time	$t_r$			20		
Turn-off Delay Time	$t_{d(off)}$			24		
Fall Time	$t_f$			50		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DD}=480V, I_D=5.5A, V_{GS}=0 \text{ to } 10V$		7.4		nC
Gate to Drain Charge	$Q_{gd}$			8.2		
Gate Charge Total	$Q_g$			25.8		
Gate Plateau Voltage	$V_{plateau}$			5.4		V
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=5.5A$		0.84	1.1	V
Reverse Recovery Time	$t_{rr}$	$V_R=400V, I_F=5.5A, dI_F/dt=100A/\mu s$		93		ns
Reverse Recovery Charge	$Q_{rr}$			0.33		$\mu C$
Peak Reverse Recovery Current	$I_{rrm}$			7.1		A

Note:

 5.  $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480V

 6.  $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480 V



Sanrise Technology Limited Company

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